
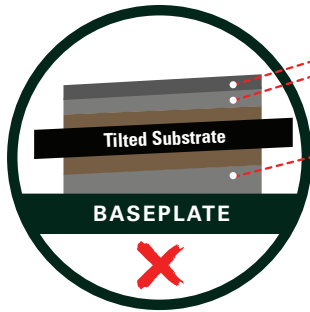


IMPROVED RELIABILITY PERFORMANCE

THE CHALLENGE: Power Module Reliability

BAD COVERAGE = BAD PERFORMANCE

- ✗  Uneven bondline thickness
- ✗  Assembly tilt and variation
- ✗  Stress concentrations

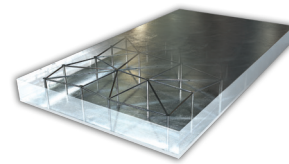


- ✗  Reduced fatigue resistance
- ✗  Premature lifecycle failures




Other Bondline Control Options

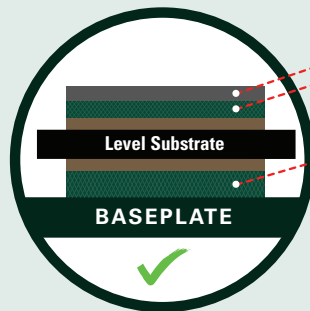
- Few standoff points → Still risk of tilt
- No reinforcement → Susceptible to movement
- Potential solder creep → Process re-design

THE SOLUTION: InFORMS® Technology



BONDLINE CONTROL = BEST PERFORMANCE

- ✓  Uniform bondline thickness
- ✓  Precise, repeatable assembly
- ✓  Even stress distribution



- ✓  Better fatigue resistance
- ✓  4X Extended lifecycle reliability performance

InFORMS® are reinforced solder preforms that deliver a uniform bondline thickness after reflow

4X LONGER LIFECYCLE

InFORMS® was developed to realize superior solder joint reliability in power module applications:

- Standoff coverage across the entire assembly → Prevent tilt and stress concentration
- Integrated matrix adds strength → Solder creep resistance
- Precise, repeatable bondline thickness → Consistent soldering performance during production
- Wide range of alloys and configurations available → Drop-in replacement for solder preforms

Learn more: www.indium.com

From One Engineer To Another®

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

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